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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Seo woo Nam	05/15/2007
Il young Yoon	05/14/2007
Jae ouk Choo	05/14/2007
Hong jae Shin	05/14/2007
Nae in Lee	05/14/2007

RECEIVING PARTY DATA

Name:	Samsung Electronics Co., Ltd.	
Street Address:	16 Maetan-dong, Yeongtong-gu	
Internal Address:	Suwon-si	
City:	Gyeonggi-do	
State/Country:	KOREA, REPUBLIC OF	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11831223

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 5649-2139

NAME OF SUBMITTER: Candi L. Riggs

PATENT

REEL: 019625 FRAME: 0134

Total Attachments: 6
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PATENT REEL: 019625 FRAME: 0135

ASSIGNMENT

THIS ASSIGNMENT, made by us, **Seo-woo Nam**, citizen of the Republic of Korea, residing at #206-205 LG APT, Seongbok-dong, Suji-gu, Yongin-si, Gyeonggi-do, Republic of Korea; **Il-young Yoon**, citizen of the Republic of Korea, residing at #1103-1101 Jugong APT., Banjeong-dong, Hwaseong-si, Gyeonggi-do, Republic of Korea; **Jae-ouk Choo**, citizen of the Republic of Korea, residing at #151-202 Kumho Bestville APT., Sanghyeondong, Suji-gu, Yongin-su, Gyeonggi-do, Republic of Korea; **Hong-jae Shin**, citizen of the Republic of Korea, residing at #101-1001 Woobang APT., 1715 Sillim 4-dong, Gwanak-gu, Seoul, Republic of Korea; and **Nae-in Lee**, citizen of the Republic of Korea, residing at #210-209 Hyundai 2-cha APT., Gaepo 4-dong, Gangnam-gu, Seoul, Republic of Korea;

WITNESSETH: That,

WHEREAS, we are the joint inventors of certain new and useful improvements in METHODS OF FORMING INTEGRATED CIRCUIT DEVICES HAVING TENSILE AND COMPRESSIVE STRESS LAYERS THEREIN AND DEVICES FORMED THEREBY for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. We hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. 11/831, 233, filed 7/31/97) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the

ASSIGNMENT - CONTINUED

term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made.

We hereby request that said Letters Patent be issued in accordance with this assignment.

We further covenant and agree that, at the time of the execution and delivery of these presents, we possess full title to the invention and application above-mentioned, and that we have the unencumbered right and authority to make this assignment.

We further covenant and agree to bind our heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to us relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN T	WITNESS WH	EREOF, I have hereunte	set my han	d and seal on this 1	5th_day
of Ma	, 200	7.			
	-	Seo-woo Nam	(SEAL)	
Witnessed	by:				
Annual An					
Date:					

ASSIGNMENT – CONTINUED

		EOF, I have hereunto	set my hand and seal on this 14th	_ day
of May	, 2007.			
		a decorate of	(SEAL)	
		ll-young Yoon	•	
Witnessed by:				
Date:				

ASSIGNMENT - CONTINUED

	IN WITNES	SS WHEREO	F, I have hereunto set i	my hand and seal on	this <u>14th</u> day
of	May	, 2007.			
		Jan	South Choo	(SEAL)	
Witnes	sed by:				
			_		
Date:					

ASSIGNMENT - CONTINUED

	IN WITN	ESS WHEREOF, I	have hereunto se	t my hand and seal on	this <u>14th</u> day
of	May	, 2007.			
			Jue Shin	(SEAL)	
Witne	essed by:				
	ve				
Date:					

ASSIGNMENT – CONTINUED

	IN WITNE	SS WHERE	OF, I have hereunt	o set my h	and and seal	on this 14th	_ day
of	May	, 2007.					
			Jae In Lee Vae-in Lee		(SEAL)		
Witnes	sed by:						
Date:							